

Amendments to the Claims: This listing of claims will replace all prior versions, and listings, of claims in the application. By this Amendment, Applicants have amended claims 1-4. Claims 1-4 are pending.

1. (As Amended) A method of forming a flip chip package, comprising:

providing a substrate member having a plurality of electrical contacts disposed thereon;

providing a flip chip having a plurality of electrical contacts disposed on a lower surface, a planar upper surface, and a plurality of edge surfaces extending between said lower and said upper surfaces;

connecting the electrical contacts of said flip chip with selected ones of the electrical contacts on a top surface of said substrate;

providing a thermally conductive planar member having a plurality of peripherally disposed edge surfaces;

[placing said thermally conductive planar member in thermally conductive communication with said upper surface of the flip chip;]

placing said thermally conductive planar member, said flip chip, and said substrate member in a mold cavity wherein a predefined portion of said substrate member cooperates with said mold cavity to define a sealable cavity;

injecting a moldable dielectric material into said sealable cavity;

curing said moldable dielectric material and thereby forming a sealed rigid dielectric covering about the edge surfaces of said thermally conductive planar member, so that said moldable dielectric material is prevented from extending below said substrate member, the edge surfaces of said flip chip, and said predefined portion of said substrate member and forming an encapsulated flip chip package comprising said thermally conductive planar member, said flip chip, and said [predefined portion of said] substrate member, and

removing said flip chip package from said [sealed covering] mold cavity.

2. (As Amended) A method of forming a flip chip package, as set forth in claim [1] 4, wherein said mold cavity has a first selected height and said thermally conductive planar member has a thickness selected so that when mounted on the upper planar surface of the flip chip, said planar member extends a second selected height being substantially equal to the first selected height of said mold cavity.

3. (As Amended) A method of forming a flip chip package, as set forth in claim [1] 4, wherein placing said thermally conductive planar member [on] in thermally conductive communication with said upper surface of the flip chip includes bonding said planar member to the upper surface of the flip chip with a thermally conductive adhesive material.

4. (Newly Added) A method of forming a flip chip package, as set forth in claim 1, further comprising the step, after providing a thermally conductive planar member, of placing said thermally conductive planar member in thermally conductive communication with said upper surface of the flip chip.